Precision, High Speed, JFET Input Operational Amplifier

DESCRIPTION

The RH1056A JFET input operational amplifiers combine precision specifications with high speed performance.

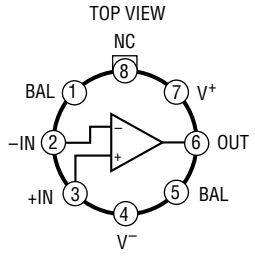
For the first time, 16V/µs slew rate and 6.5MHz gain-bandwidth product are simultaneously achieved with offset voltage of typically 50µV, 1.2µV/°C drift, bias currents of 40pA at 70°C.

The wafer lots are processed to LTC's in-house Class S flow to yield circuits usable in stringent military applications.

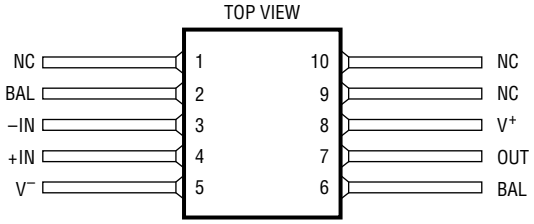
ABSOLUTE MAXIMUM RATINGS

Supply Voltage ..... ±20V
Differential Input Voltage ..... ±40V
Input Voltage ..... ±20V
Output Short-Circuit Duration ..... Indefinite
Operating Temperature Range ..... –55°C to 125°C
Storage Temperature Range ..... –65°C to 150°C
Lead Temperature (Soldering, 10 sec) ..... 300°C

PACKAGE/ORDER INFORMATION

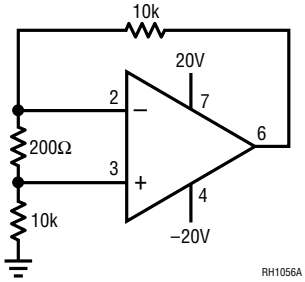


H PACKAGE
8-LEAD TO-5 METAL CAN



W PACKAGE
10-LEAD CERPAC

BURN-IN CIRCUIT



TOTAL DOSE BIAS CIRCUIT

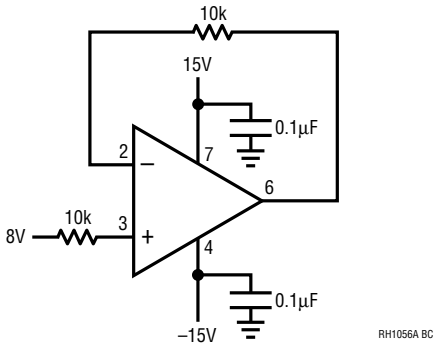


TABLE 1: ELECTRICAL CHARACTERISTICS (Preirradiation) (Note 2)

SYMBOL	PARAMETER	CONDITIONS	NOTES	$T_A = 25°C$ MIN	TYP	MAX	SUB-GROUP	$-55°C \le T_A \le 125°C$ MIN	TYP	MAX	SUB-GROUP	UNITS
V_{OS}	Input Offset Voltage		1			300	4			700	2, 3	µV
I_{OS}	Input Offset Current	Fully Warmed Up $T_A = 125°C$	3 3			10	1			 1.5	 2	pA nA
I_B	Input Bias Current	Fully Warmed Up $T_A = 125°C$	3			50	1			 3.0	 2	pA nA
R_{IN}	Input Resistance				10^{12}							Ω
A_{VOL}	Large-Signal Voltage Gain	$V_S = ±15V$, $V_O = ±10V$, $R_L = 2k$ $V_S = ±15V$, $V_O = ±10V$, $R_L = 1k$		150 130			4 4	40			5,6	V/mV V/mV
V_O	Output Voltage Swing	$V_S = ±15V$, $R_L = 2k$		±12			4	±12			5,6	V
V_{CM}	Input Common Mode Voltage Range	$V_S = ±15V$		±11			1	±11			2,3	V
CMRR	Common Mode Rejection Ratio	$V_{CM} = ±11V$ $V_{CM} = ±10.5V$		86			1	 85			 2,3	dB dB
PSRR	Power Supply Rejection Ratio	$V_S = ±10V$ to $±18V$ $V_S = ±10V$ to $±17V$		90			1	 88			 2,3	dB dB
I_S	Supply Current	$V_S = ±15V$				6.5	1					mA
SR	Slew Rate	$A_V = 1$, $V_S = ±15V$		12			7					V/µs
GBW	Gain-Bandwidth Product	$V_S = ±15V$			6.5							MHz
e_n	Input Noise Voltage Density	$V_S = ±15V$, f = 10Hz $V_S = ±15V$, f = 1kHz			28 14							nV/√Hz nV/√Hz
i_n	Input Noise Current Density	$V_S = ±15V$, f = 10Hz $V_S = ±15V$, f = 1kHz			1.8 1.8							fA/√Hz fA/√Hz
C_{IN}	Input Capacitance				4				4			pF

TABLE 1A: ELECTRICAL CHARACTERISTICS (Postirradiation) (Note 4)

SYMBOL	PARAMETER	CONDITIONS	NOTES	10KRAD(Si) MIN	10KRAD(Si) MAX	25KRAD(Si) MIN	25KRAD(Si) MAX	50KRAD(Si) MIN	50KRAD(Si) MAX	100KRAD(Si) MIN	100KRAD(Si) MAX	200KRAD(Si) MIN	200KRAD(Si) MAX	UNITS
V_{OS}	Input Offset Voltage		1		300		300		370		570		570	µV
I_{OS}	Input Offset Current		3		±10		±50		±150		±250		±350	pA
I_B	Input Bias Current		3		±50		±250		±500		±1000		±2000	pA
A_{VOL}	Large-Signal Voltage Gain Large-Signal Voltage Gain	V_O = ±10V, R_L ≥ 2k V_O = ±10V, R_L ≥ 1k		150 130		150 130		150 130		100 87		75 65		V/mV V/mV
V_O	Output Voltage Swing	R_L ≥ 2k		±12		±12		±12		±12		±12		V
V_{CM}	Input Common Mode Voltage Range	V_S = ±15V		±11		±11		±11		±11		±11		V
CMRR	Common Mode Rejection Ratio	V_{CM} = ±11V		86		86		86		86		86		dB
PSRR	Power Supply Rejection Ratio	V_S = ±10V to ±18V		90		90		90		90		90		dB
I_S	Supply Current				7		7		7		7		7	mA
SR	Slew Rate	A_V = 1, V_S = ±15V		12		12		12		12		12		V/µs
C_{IN}	Input Capacitance			3(Typ)		3(Typ)		3(Typ)		3(Typ)		3(Typ)		pF

Note 1: Unless otherwise specified, the absolute maximum negative input voltage is equal to the negative power supply voltage. Offset voltage is measured under two different conditions: (a) approximately 0.5 seconds after application of power, (b) at T_A = 25°C only, with the chip heated to approximately 45°C to account for chip temperature rise when the device is fully warmed up.

Note 2: Unless otherwise stated, V_S = ±15V; and V_{OS}, I_B and I_{OS} are measured at V_{CM} = 0V.

Note 3: The input bias currents are junction leakage currents which approximately double for every 10°C increase in the junction temperature, T_J. Due to limited production test time, the input bias currents measured are correlated to junction temperature. In normal operation the junction temperature rises above the ambient temperature as a result of internal power dissipation, P_D. $T_J = T_A + (\theta_{JA} \bullet P_D)$ where θ_{JA} is the thermal resistance from junction to ambient.

Note 4: Unless otherwise stated, V_S = ±15V, V_{CM} = 0V and T_A = 25°C.

TABLE 2: ELECTRICAL TEST REQUIREMENTS

MIL-STD-883 TEST REQUIREMENTS	SUBGROUP
Final Electrical Test Requirements (Method 5004)	1*,2,3,4,5,6,7
Group A Test Requirements (Method 5005)	1,2,3,4,5,6,7
Group B and D for Class S, and Class C and D for Class B End Point Electrical Parameters (Method 5005)	1

* PDA applies to subgroup 1. See PDA Test Notes.

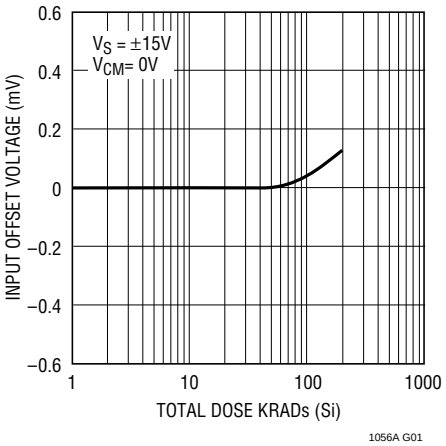
PDA Test Notes

The PDA is specified as 5% based on failures from group A, subgroup 1, tests after cooldown as the final electrical test in accordance with method 5004 of MIL-STD-883. The verified failures of group A, subgroup 1, after burn-in divided by the total number of devices submitted for burn-in in that lot shall be used to determine the percent for the lot.

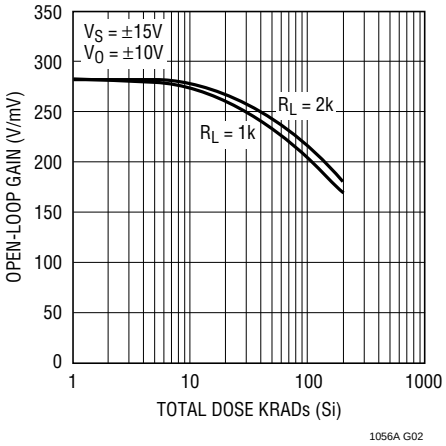
Linear Technology Corporation reserves the right to test to tighter limits than those given.

TYPICAL PERFORMANCE CHARACTERISTICS

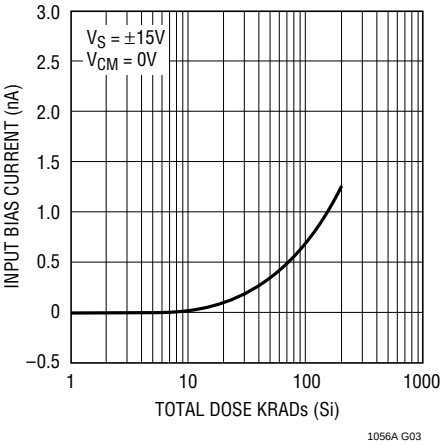
Input Offset Voltage



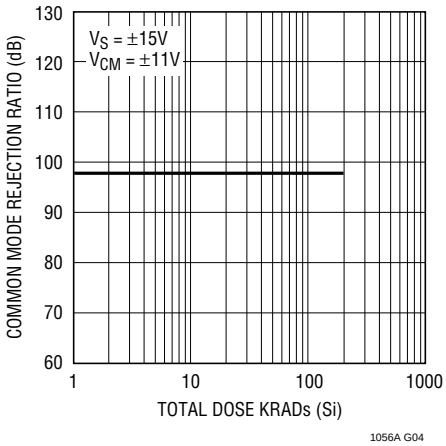
Open-Loop Gain



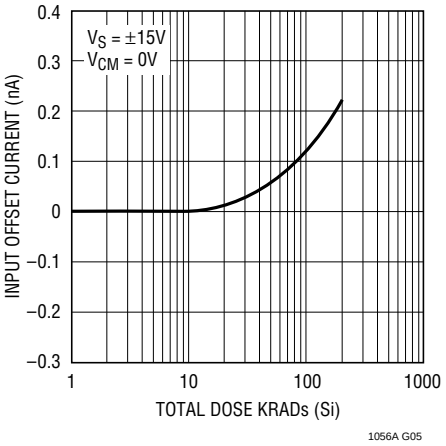
Input Bias Current



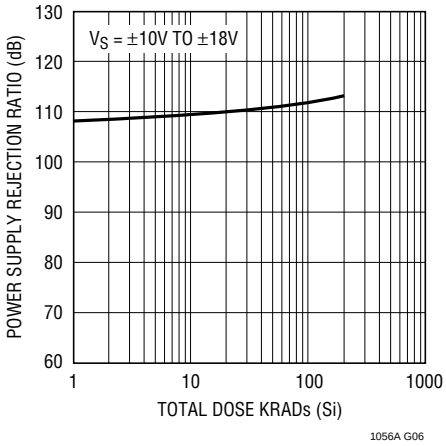
Common Mode Rejection Ratio



Input Offset Current



Power Supply Rejection Ratio



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